Remarks

Claims 1, 2 and 8-19 are currently pending.

35 U.S.C. § 103

The Examiner rejected claims 1, 2, 8-10, 14-15 and 17 under 35 U.S.C. § 103(a) as being unpatentable over Wozniak (US Pat. No. 4,851,464). The Examiner also rejected claims 11-13 and 16 as being unpatentable over Wozniak in view of Leoni et al. (US Pat. No. 4,717,716) and claims 18-19 as being unpatentable over Wozniak in view of Burba et al. (US Pat. No. 4,440,900). Applicants traverse these rejections for the following reasons.

Applicants presently claimed invention is directed to an adhesion promoter for plastisols, characterized in that the adhesion promoter consists essentially of a polyaminoamide and 10 % - 60 % by weight of ethyldiglycol based on the total weight of adhesion promoter.

In comparison, Wozniak teaches an adhesion promoter system containing a polyaminoamide, a primary plasticizer and a secondary plasticizer non-ionic solvent. Wozniak neither teaches nor suggests eliminating the primary plasticizer to form an adhesion promoter system containing only the polyaminoamide and secondary plasticizer non-ionic solvent, but instead asserts the improvement that its invention provides is a system comprising the combination of the polyaminoamide, the primary plasticizer, and the secondary plasticizer non-ionic solvent. *See U.S. Pat. No. 4,851,464* at col. 2, ll. 11-15.

Moreover, Wozniak teaches the amount of secondary plasticizer non-ionic solvent in the plasticizer/promoter phase is an amount "effective to solvate" the polyaminoamide,

this amount being in a range from 10-70 weight parts per 100 weight parts of PVC resin. *See id.* at col. 3, ll. 7-13. In comparison, the amount of ethyldiglycol in Applicants claimed invention is 10% - 60% by weight based on the total weight of adhesion promoter. Thus, this amount is significantly less than the amount taught in Wozniak. Wozniak neither teaches nor suggests that such low amounts of non-ionic solvent could or would be effective in an adhesion promoter system. In fact, Wozniak indicates in the Examples that amounts of at least 40 weight parts of non-ionic solvent per 100 weight parts of PVC resin may be required.

Nevertheless, the Examples provided in the present application demonstrate that unexpectedly good adhesion can be achieved by combining the presently claimed low amounts of ethyldiglycol with polyaminoamide to form an adhesion promoter useful in a plastisol composition (*see US 2007/0043153* at paragraphs [0031] to [0041]). In particular, the plastisol composition of Example 3, which contained the polyaminoamide and only 0.4% of ethyldiglycol based on the total weight of the plastisol composition, exhibited surprisingly good adhesion. Additionally, high temperature storage stability and processability for the plastisol composition of Example 3 were vastly better than those exhibited for plastisol compositions which did not contain ethyldiglycol. Such results were not foreseeable. Therefore, in view of the above, Applicants respectfully request the rejections based on Wozniak be withdrawn.

Adding the teachings of Leoni et al. or Burba et al. also does not bring one skilled in the art closer to Applicants invention. Leoni et al. and Burba et al. were added for the purpose of teaching the addition of certain amounts of the adhesion promoter by weight to the plastisol composition. Leoni et al. and Burba et al. neither teach nor suggest the

addition of an adhesion promoter consisting essentially of a polyaminoamide and 10% - 60% by weight of ethyldiglycol based on the total weight of the adhesion promoter. Thus, for the reasons set forth above, Applicants respectfully request the rejections based on Wozniak, Leoni et al. and Burba et al. be withdrawn.

The Commissioner of Patents is hereby authorized to deduct any fee due in connection with the filing of this document from Huntsman Corporation Deposit Account No. 08-3442.

Respectfully Submitted,

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